



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20220630000.0
Datasheet for SNx4HC112, SNx4HC175, SNx4HC368, and CDx4HCT373
Information Only

Date: July 05, 2022
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74HC175NSR	null
SN74HC175N	null
SN74HC175PWR	null
SN74HC368NSR	null
SN74HC112N	null

Technical details of this Product Change follow on the next page(s).

Notification Number:	20220630000.0	Notification Date:	July 05, 2022
Title:	Datasheet for SNx4HC112, SNx4HC175, SNx4HC368, and CDx4HCT373		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



SN54HC112, SN74HC112

SCLS099H – DECEMBER 1982 – REVISED JUNE 2022

Changes from Revision G (February 2022) to Revision H (June 2022)

Page

- Junction-to-ambient thermal resistance values increased. D was 73 is now 117.2, N was 67 is now 89.1.....4



SN54HC175, SN74HC175

SCLS299F – JANUARY 1996 – REVISED JUNE 2022

Changes from Revision E (February 2022) to Revision F (June 2022)

Page

- Junction-to-ambient thermal resistance values increased. D was 73 is now 117.2, DB was 67 is now 102.7, N was 82 is now 60.5, NS was 64 is now 88.6, PW was 108 is now 137.5.....4



SN54HC368, SN74HC368

SCLS310F – JANUARY 1996 – REVISED JUNE 2022

Changes from Revision E (February 2022) to Revision F (June 2022)

Page

- Junction-to-ambient thermal resistance values increased. D was 73 is now 117.2, N was 67 is now 68.6, NS was 64 is now 87.4, PW was 108 is now 137.5.....4



CD54HCT373, CD74HCT373

SCLS453E – FEBRUARY 2001 – REVISED JUNE 2022

Changes from Revision D (February 2022) to Revision E (June 2022)

Page

- Junction-to-ambient thermal resistance values increased. DW was 69 is now 109.1, N was 58 is now 84.6.....4

The datasheet number will be changing.

Device Family	Change From:	Change To:
SNx4HC112	SCLS099G	SCLS099H
SNx4HC175	SCLS299E	SCLS299F
SNx4HC368	SCLS310E	SCLS310F
CDx4HCT373	SCLS453D	SCLS453E

These changes may be reviewed at the datasheet links provided.

<https://www.ti.com/product/SN74HC112>

<https://www.ti.com/product/SN74HC175>

<https://www.ti.com/product/SN74HC368>

<https://www.ti.com/product/CD74HCT373> **Error! Bookmark not defined.**

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

CD74HCT373E	SN74HC112DT	SN74HC175NE4	SN74HC368DR	
CD74HCT373M	SN74HC112N	SN74HC175NSR	SN74HC368N	
CD74HCT373M96	SN74HC175D	SN74HC175PW	SN74HC368NE4	
CD74HCT373M96G4	SN74HC175DBR	SN74HC175PWR	SN74HC368NSR	
CD74HCT373MG4	SN74HC175DG4	SN74HC368D	SN74HC368PW	
SN74HC112D	SN74HC175DR	SN74HC368DG4	SN74HC368PWR	
SN74HC112DR	SN74HC175N			

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

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